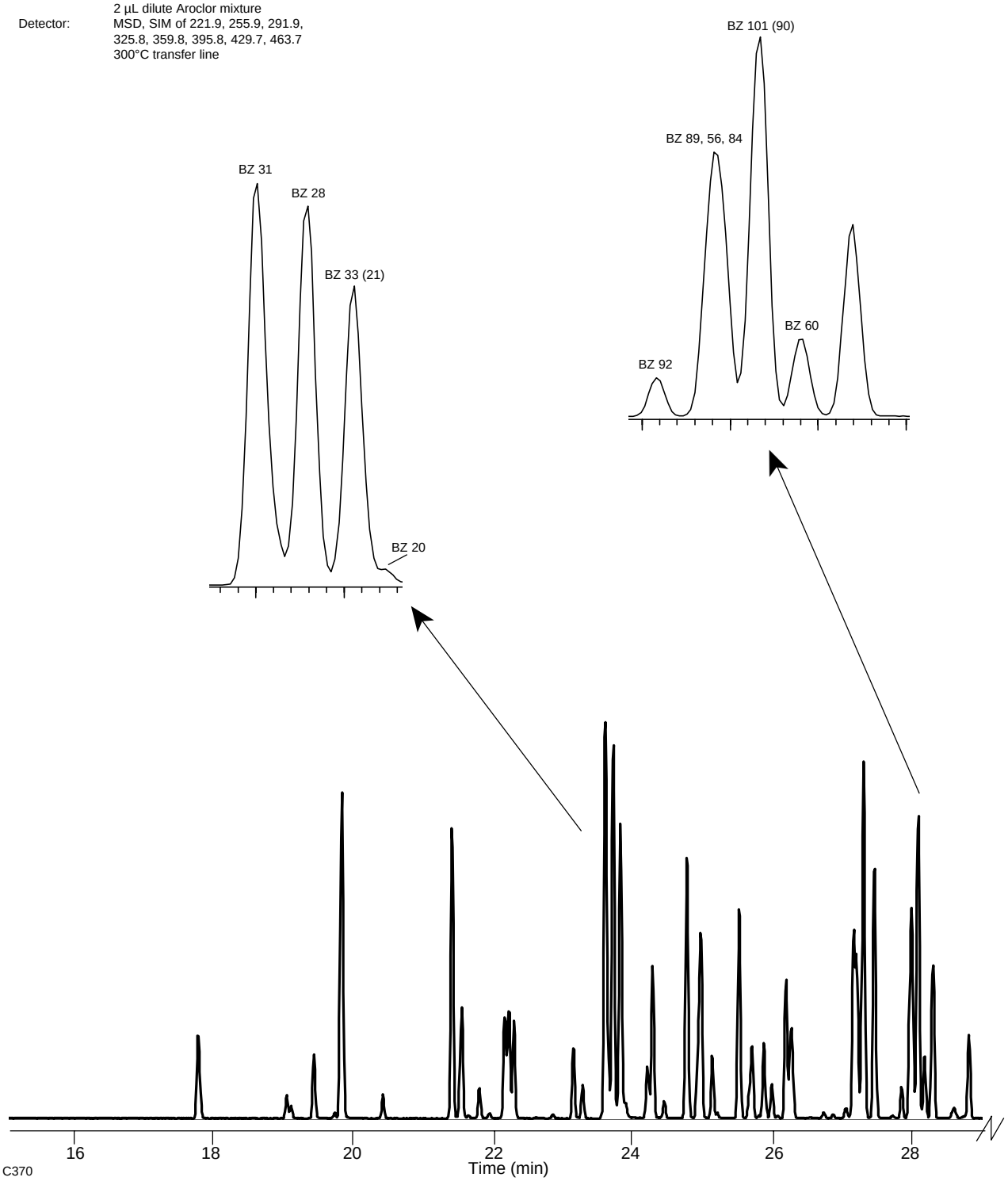
Congeners in DIN Method PCBs

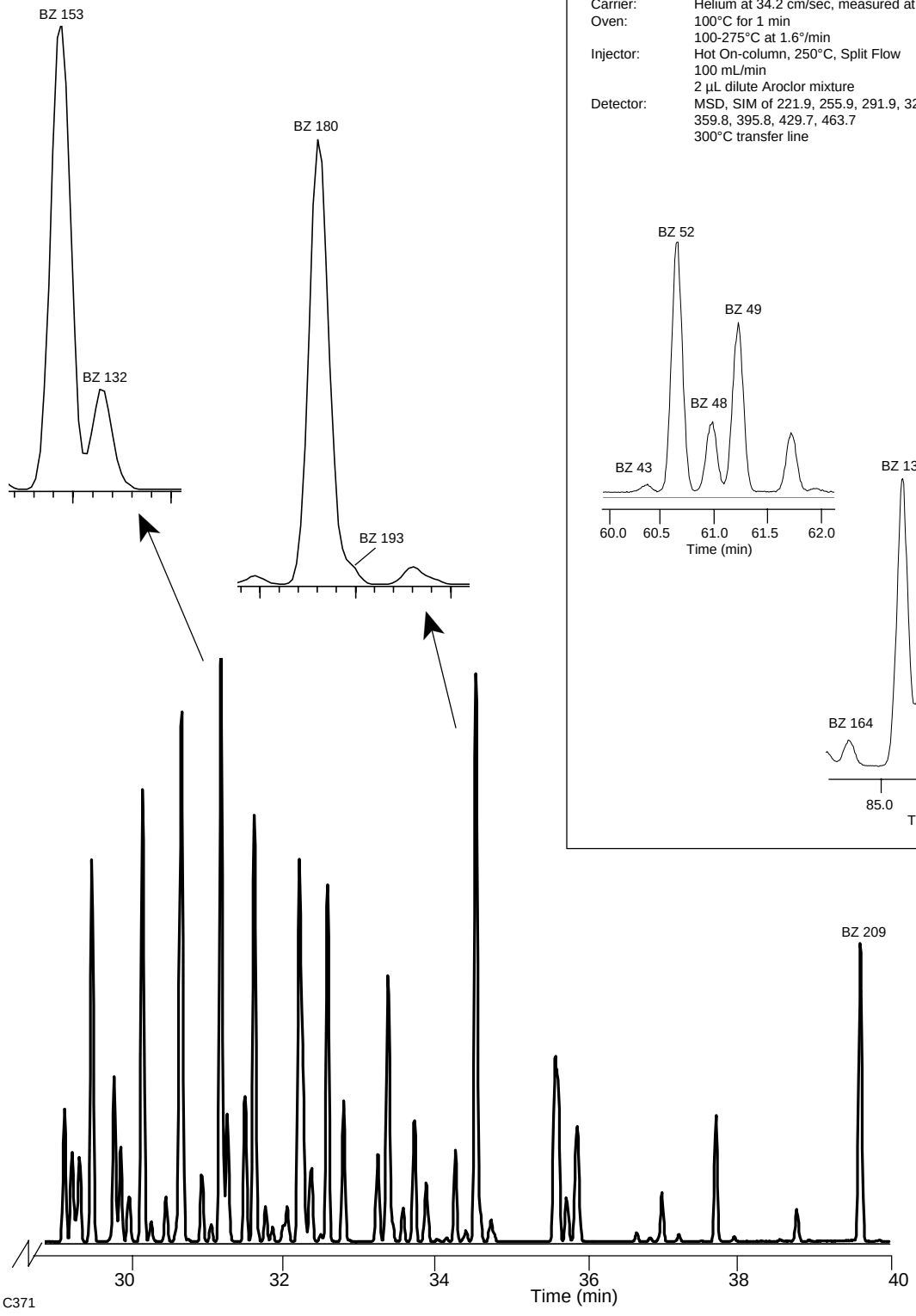
Column:	**DB-XLB**
	30 m x 0.25 mm I.D., 0.5 µm
	1 m x 0.53 mm I.D. Retention Gap
J&W P/N:	**122-1236**
Carrier:	Helium at 34.2 cm/sec, measured at 150°C
Oven:	100°C for 1 min
	100-320°C at 5.6°/min
Injector:	Hot On-column, 250°C, Split Flow
	100 mL/min
	2 µL dilute Aroclor mixture
Detector:	MSD, SIM of 221.9, 255.9, 291.9,
	325.8, 359.8, 395.8, 429.7, 463.7
	300°C transfer line



C370

Extended Temperature Program Resolving Congeners 52 and 138

Column:	**DB-XLB**
	30 m x 0.25 mm I.D., 0.5 µm
	1 m x 0.53 mm I.D. Retention Gap
J&W P/N:	**122-1236**
Carrier:	Helium at 34.2 cm/sec, measured at 150°C
Oven:	100°C for 1 min
	100-275°C at 1.6°/min
Injector:	Hot On-column, 250°C, Split Flow
	100 mL/min
	2 µL dilute Aroclor mixture
Detector:	MSD, SIM of 221.9, 255.9, 291.9, 325.8, 359.8, 395.8, 429.7, 463.7
	300°C transfer line



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